MA2Q736 (MA736)

Silicon epitaxial planar type

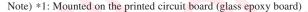
For high frequency rectification

■ Features

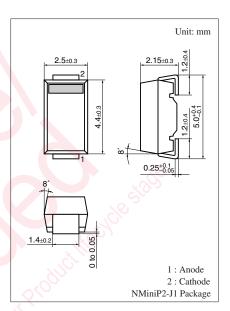
- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible
- Reverse voltage $V_R = 40 \text{ V}$ is guaranteed
- Automatic insertion with the emboss taping is possible

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RRM}	40	V
Forward current (Average) *1	I _{F(AV)}	1	A
Non-repetitive peak forward surge current *2	I_{FSM}	30	A
Junction temperature	T_{j}	-40 to +125	°C
Storage temperature	T_{stg}	-40 to +125	°C ,



^{*2:} The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

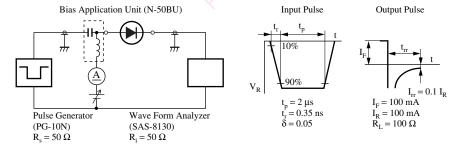


Marking Symbol: PB

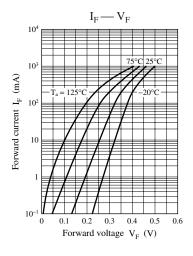
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

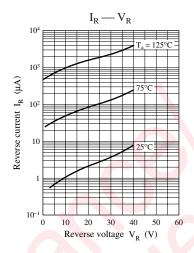
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 1.0 \text{ A}$		SO.	0.55	V
Reverse current	I_R	$V_R = 40 \text{ V}$		J.	2	mA
Terminal capacitance	Ct	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$	1.9	50		pF
Reverse recovery time	t _{rr} *	$I_F = I_R = 100 \text{ mA}$			30	ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

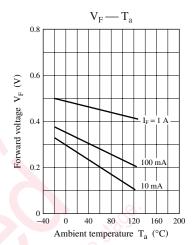
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 20 MHz.
 - 4. *: t_{rr} measurement circuit

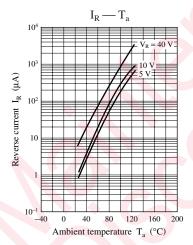


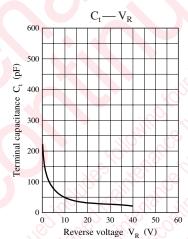
Note) The part number in the parenthesis shows conventional part number.

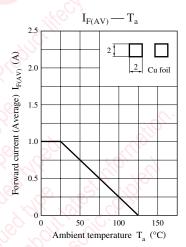












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